

# **LM1877 Dual Audio Power Amplifier**

Check for Samples: LM1877

### **FEATURES**

- 2W/Channel
- -65 dB Ripple Rejection, Output Referred
- -65 dB Channel Separation, Output Referred
- Wide Supply Range, 6V-24V
- **Very Low Cross-Over Distortion**
- **Low Audio Band Noise**
- **AC Short Circuit Protected**
- Internal Thermal Shutdown

#### **APPLICATIONS**

- **Multi-Channel Audio Systems**
- Stereo Phonographs
- **Tape Recorders and Players**
- **AM-FM Radio Receivers**
- **Servo Amplifiers**
- **Intercom Systems**
- Automotive Products

# Connection Diagram

## DESCRIPTION

The LM1877 is a monolithic dual power amplifier designed to deliver 2W/channel continuous into 8Ω loads. The LM1877 is designed to operate with a low number of external components, and still provide flexibility for use in stereo phonographs, tape recorders and AM-FM stereo receivers. Each power amplifier is biased from a common internal regulator to provide high power supply rejection, and output Q centering. The LM1877 is internally compensated for all gains greater than 10.

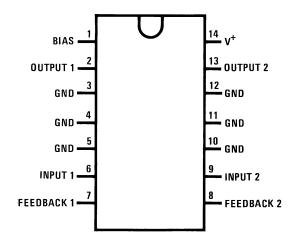
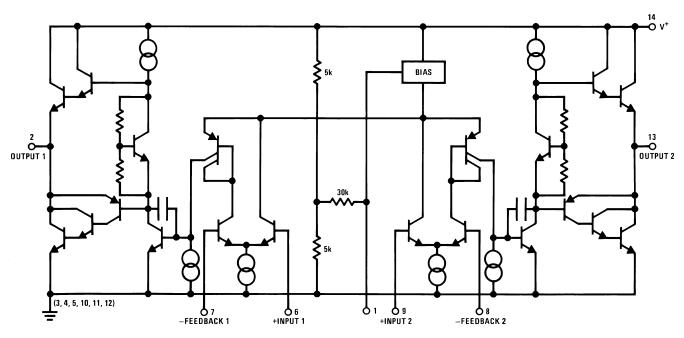


Figure 1. 14-Pin SOIC or PDIP (Top View) See NPA0014B or NFF0014A Package

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## **Equivalent Schematic Diagram**





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

# Absolute Maximum Ratings (1)(2)

Absolute maximum ratings		
Supply Voltage		26V
Input Voltage		±0.7V
Operating Temperature	0°C to +70°C	
Storage Temperature		−65°C to +150°C
Junction Temperature		150°C
Lead Temperature	PDIP Package Soldering (10 sec.)	260°C
	SOIC Package Infrared (15 sec.)	220°C
	SOIC Package Vapor Phase (60 sec.)	215°C
Thermal Resistance	θ <sub>JC</sub> (PDIP Package)	30°C/W
	θ <sub>JA</sub> (PDIP Package)	79°C/W
	θ <sub>JC</sub> (SOIC Package)	27°C/W
	θ <sub>JA</sub> (SOIC Package)	114°C/W

<sup>(1)</sup> Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.

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<sup>(2)</sup> If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.



## **Electrical Characteristics**

 $V_S$  = 20V,  $T_A$  = 25°C<sup>(1)</sup>  $R_L$  = 8 $\Omega$ ,  $A_V$  = 50 (34 dB) unless otherwise specified

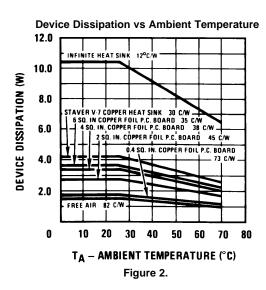
Parameter	Conditions	Min	Тур	Max	Units
Total Supply Current	$P_0 = 0W$		25	50	mA
Output Power	THD = 10%				
LM1877	$V_S = 20V, R_L = 8\Omega$	2.0			W/Ch
	$V_S = 12V$ , $R_L = 8\Omega$		1.3		W/Ch
Total Harmonic Distortion	f = 1 kHz, V <sub>S</sub> = 14V				
LM1877	P <sub>O</sub> = 50 mW/Channel		0.075		%
	P <sub>O</sub> = 500 mW/Channel		0.045		%
	P <sub>O</sub> = 1 W/Channel		0.055		%
Output Swing	$R_L = 8\Omega$		V <sub>S</sub> -6		Vp-p
Channel Separation	$C_F = 50 \mu F, C_{IN} = 0.1 \mu F,$				
	f = 1 kHz, Output Referred				
	$V_S = 20V$ , $V_O = 4$ Vrms	-50	<b>-7</b> 0		dB
	$V_S = 7V$ , $V_O = 0.5$ Vrms		-60		dB
PSRR Power Supply	$C_F = 50 \mu F, C_{IN} = 0.1 \mu F,$				
Rejection Ratio	f = 120 Hz, Output Referred				
	$V_S = 20V$ , $V_{RIPPLE} = 1 Vrms$	-50	-65		dB
	$V_S = 7V$ , $V_{RIPPLE} = 0.5 Vrms$		-40		dB
Noise	Equivalent Input Noise				
	$R_S = 0$ , $C_{IN} = 0.1 \mu F$ ,		2.5		μV
	BW = 20 Hz-20 kHz, Output Noise Wideband				
	$R_S = 0$ , $C_N = 0.1 \mu F$ , $A_V 200$		0.80		mV
Open Loop Gain	$R_S = 0$ , $f = 100 \text{ kHz}$ , $R_L = 8\Omega$		70		dB
Input Offset Voltage			15		mV
Input Bias Current			50		nA
Input Impedance	Open Loop		4		МΩ
DC Output Level	tput Level $V_S = 20V$ 9 10 11		11	V	
Slew Rate			2.0		V/µs
Power Bandwidth			65		kHz
Current Limit			1.0		Α

<sup>(1)</sup> For operation at ambient temperature greater than 25°C, the LM1877 must be derated based on a maximum 150°C junction temperature.

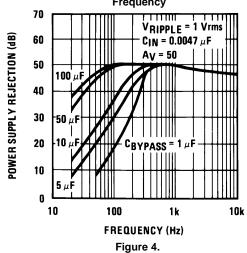
Product Folder Links: LM1877



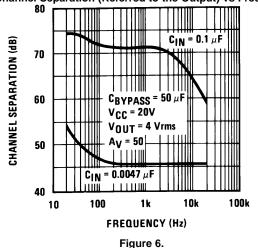
### Typical Performance Characteristics



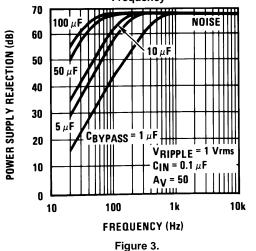
Power Supply Rejection Ratio (Referred to the Output) vs Frequency



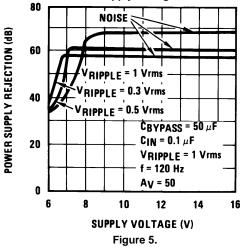
Channel Separation (Referred to the Output) vs Frequency



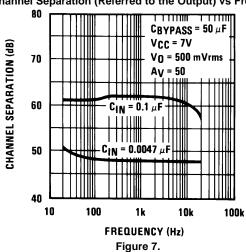
Power Supply Rejection Ratio (Referred to the Output) vs Frequency



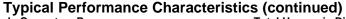
Power Supply Rejection Ratio (Referred to the Output) vs Supply Voltage

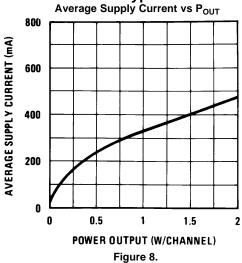


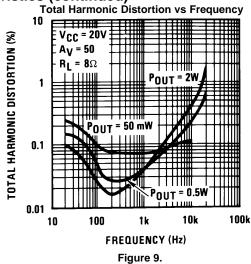
Channel Separation (Referred to the Output) vs Frequency

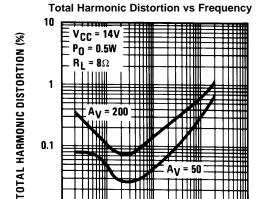










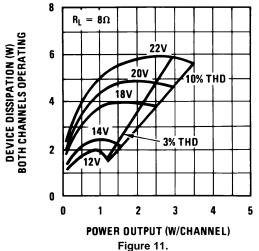


0.01

10

100

Power Dissipation (W) Both Channels Operating

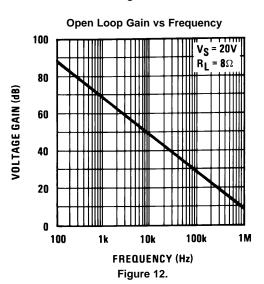


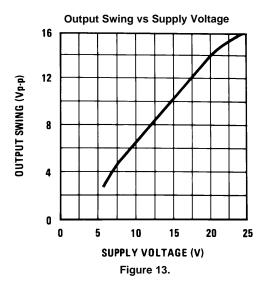


1k

10k

100k







# **Typical Applications**

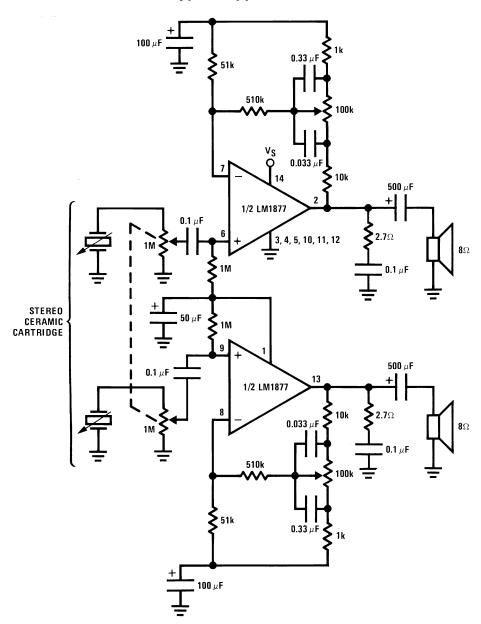
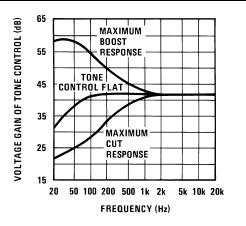


Figure 14. Stereo Phonograph Amplifier with Bass Tone Control





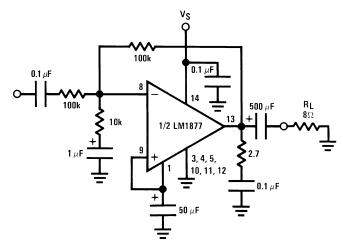


Figure 15. Frequency Response of Bass Tone Control

Figure 16. Inverting Unity Gain Amplifier

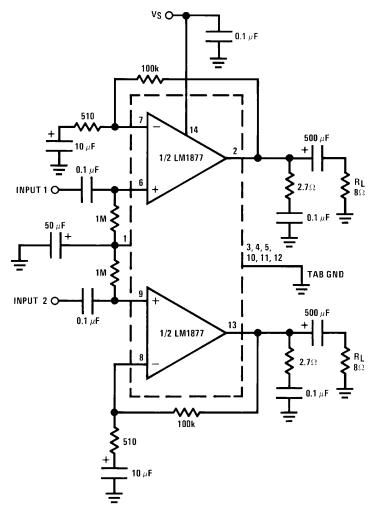


Figure 17. Stereo Amplifier with  $A_V = 200$ 



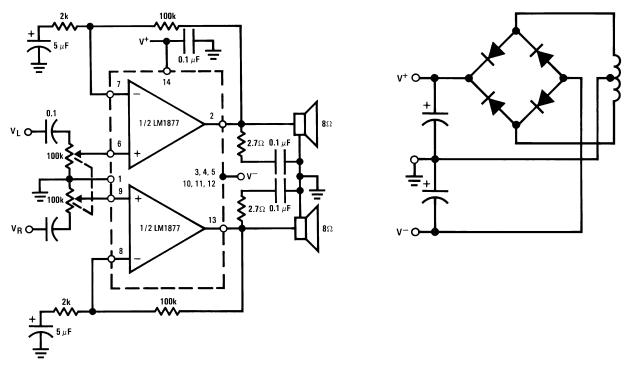


Figure 18. Non-Inverting Amplifier Using Split Supply

Figure 19. Typical Split Supply



## **REVISION HISTORY**

CI	hanges from Revision A (April 2013) to Revision B	Page
•	Changed layout of National Data Sheet to TI format	7

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
LM1877MX-9/NOPB	Active	Production	SOIC (NPA)   14	1000   LARGE T&R	Yes	SN	Level-3-260C-168 HR	0 to 70	LM1877M -9
LM1877MX-9/NOPB.B	Active	Production	SOIC (NPA)   14	1000   LARGE T&R	Yes	SN	Level-3-260C-168 HR	0 to 70	LM1877M -9

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

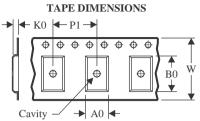
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE MATERIALS INFORMATION**

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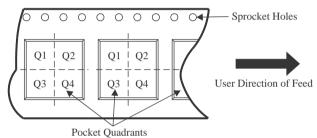
## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

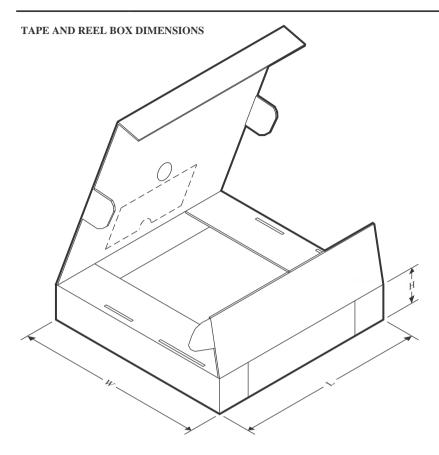
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

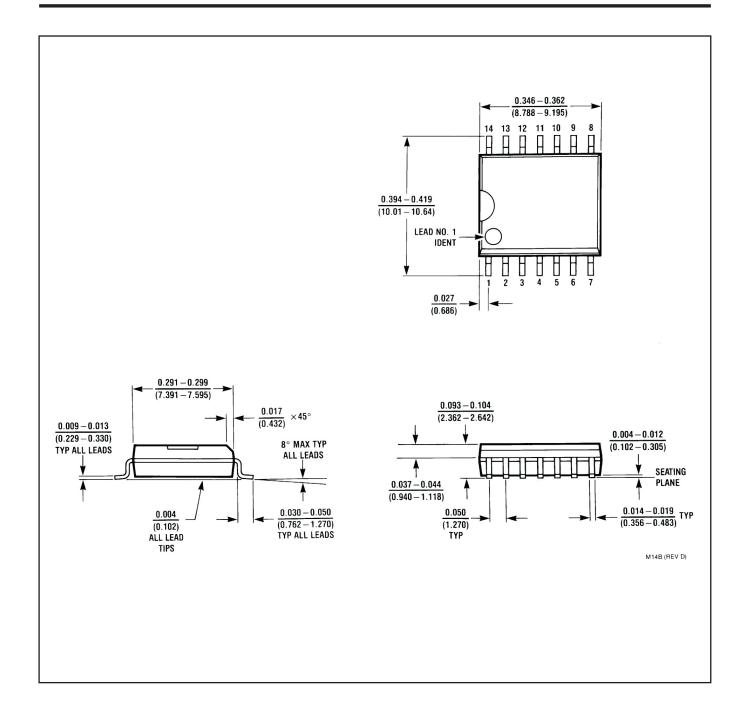
Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM1877MX-9/NOPB	SOIC	NPA	14	1000	330.0	16.4	10.9	9.5	3.2	12.0	16.0	Q1

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### \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	LM1877MX-9/NOPB	SOIC	NPA	14	1000	356.0	356.0	36.0	





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